

13.56 MHz 64 Data bit Read Only Contactless Identification Device

Description

The EM4006 (previously named H4006) is a CMOS integrated circuit intended for use in electronic Read Only transponders.

The exited coil connected to the device generates the power supply via a rectifier and an integrated decoupling capacitor. The clock used for the logic is also extracted from the coil. The logic is mainly composed by a miller code generator and the LROM control. The memory is factory programmed so that each IC is unique.

Features

- Operating frequency range 10 MHz to 15 MHz
- RF interface optimized for 13.56 MHz operation
- Laser programmed memory array
- (64 data bit + 16 CRC bit)
- Modulator switch designed to preserve supply voltage
- Miller coding
- Default data rate is 26484 Baud
- Other data rates possible (mask programmable)
- On chip rectifier
- On chip resonant capacitor
- On chip supply buffer capacitor

Applications

- Logistics automation
- Anticounterfeiting

Pad Assignment

- Access control
- Industrial transponder

Typical Operating Configuration

Coil1

Coil2

L: typical 1.4μ H for fo = 13.56MHz

EM4006



Fig. 1





Absolute Maximum Ratings

Parameter	Symbol	Conditions
Maximum DC Current forced on COIL1 and COIL2	I _{CMAX}	±30mA
Power Supply	V _{DD}	-0.3V to 7.5V
Storage Temp. Die form	T _{st}	-55 to +200°C
Storage Temp. PCB form	T _{st}	-55 to +125°C
Electrostatic discharge maximum to MIL-STD-883C method 3015	V_{ESD}	2000V

Stresses above these listed maximum ratings may cause permanent damages to the device. Exposure beyond specified operating conditions may affect device reliability or cause malfunction.

Handling Procedures

This device has built-in protection against high static voltages or electric fields; however, anti-static precautions must be taken as for any other CMOS component. Unless otherwise specified, proper operation can only occur when all terminal voltages are kept within the voltage range. Unused inputs must always be tied to a defined logic voltage level.

Operating Conditions

Parameter	Symb	Min	Тур	Max	Units
Operating Temp.	Тор	-40		+85	°C
Maximum Coil Current	Icoil	-10		10	mA
AC Voltage on Coil	Vcoil	3	14*		Vpp
Supply Frequency	fcoil	10	13.56	15	MHz

*) The AC Voltage on Coil is limited by the on chip voltage limitation circuitry. This is according to the parameter Icoil.







Electrical Characteristics

 V_{DD} = 2V, V_{SS} = 0V, f_{C1} = 13.56MHz sine wave, V_{C1} = 1.0Vpp centered at $(V_{DD} - V_{SS})/2$, T_a = 25°C unless otherwise specified

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Supply Voltage	V _{DD}		1.9		(note 1)	V
Supply current	I _{DD}			60	150	μA
Rectifier Voltage Drop	V _{REC}	I_{C1C2} = 1mA, modulator switch on V_{REC} = (V_{C1} - V_{C2}) - (V_{DD} - V_{SS})			1.8	V
Modulator ON DC voltage drop (note 2)	V _{ON1} V _{ON2}	I _{VDD VSS} = 1mA I _{VDD VSS} = 10mA	1.9 2.4	2.3 2.8	2.8 3.3	V V
Power on reset (note 3)	V _R V _R - V _{MIN}		1.2 0.1	1.4 0.25	1.7 0.5	V V
Coil1 - Coil2 Capacitance	C _{RES}	V _{coil} =100mVRMS f=10kHz	92.6	94.5	96.4	pF
Series resistance of C_{RES}	Rs			3		Ω
Power Supply Capacitor	C_{sup}			140		pF
	1					1 1

Note 1: Maximum voltage is defined by forcing 10 mA on C1 - C2

Note 2: Measured between VDD and VSS

Note 3: According to Figure 7

Block Diagram





General Description

The transponder will be activated when illuminated by a RF field of sufficient power and at any frequency that is compatible with its associated antenna and its internal power supply circuit input characteristics. The chip will Power-on-Reset itself when powered by this incoming energy that exceeds its reset threshold. After resetting itself the chip will start to transmit its memory contents as a stream of Miller code. The memory contents is transmitted by modifying the antenna matching impedance at its internal clock rate, thereby causing varying amounts of RF energy to be reflected from the antenna. This impedance variation will be achieved by connecting a modulating device across the antenna terminals. When switched on the modulating device will present a low impedance to the antenna. This will cause a change in the matching of the antenna and therefore in the amount of RF energy reflected by the transponder to the reader. This reflected signal combines with the transmitted signal in the receiver to yield an amplitude modulated signal representative of the IC memory contents. The "ON" impedance of the modulating device needs to be comparable to about 100 Ohms to affect the matching of the antenna and therefore its reflectivity.

The RF signal received from the transponder antenna will serve several purposes :

- power the chip
- provide a global reset to the chip through its POR (Power-On-Reset) function
- provide a carrier for the data transmission
- provide the input of the internal clock generation circuit (frequency division)

Functional Description Output Sequence

Transmission from the transponder will be accomplished through variation of the antenna load impedance by switching the modulating device ON and OFF.

Output sequence is composed of cycles which are repeated. Each cycle is composed of 82 bits Standard Message Structure (STDMS) which is Miller coded and a pause (LW) during which the modulating device is OFF (see figure 6 for details of Miller code).

The pause (LW) is 9bits length.

The 82 bit STDMS consists of 1 start bit, 64 data bits, 16 CRC bits and 1 stop bit.

Start bit (1)	Data(64)	CRC (16)	Stop bit (1)	LW(9)

Memory organisation

As already mentioned above the 82 bits are stored in laser programmed ROM (LROM). The 82 bits of this LROM is particular followed (see Memory Map):

Factory reserved	9 bits
IC name	10 bits
Customer ID	13 bits
ID code	32 bits
CRC-CCITT	16 bits
Start and stop bits	2 bits

irst	out)																_
0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
tart		Factory reserved MSB IC Name									_						
																-	-
	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	
			LSB	MSB					Cu	stome	r ID					LSB	
-			-	-	-			-			-		-			-	-
	33	34	35	36	37	38	39	40	41	42	43	44	45	46	47	48	
	MSB							I	D cod	е							-
						1	1		1					1			-
	49	50	51	52	53	54	55	56	57	58	59	60	61	62	63	64	
_							I	D cod	е							LSB	
						1	1		1					1			
	65	66	67	68	69	70	71	72	73	74	75	76	77	78	79	80	81
	LSB						(CRC -	CCIT	Т						MSB	Sto

Memory Map





Factory reserved bits

These 9 bits are reserved. Default value is 00Bhex.

IC name bits

They contains the 3 last characters device name. For this device, the value is 006hex.

Customer ID bits

This field contains a code which is defined by EM Microelectronic-Marin S.A. For standard version, the code is 0001hex.

ID code bits

This field is programmed from a counter in that way that each device is unique.

Cyclic redundancy check

The shift register is reset to all zero with each Stop Bit. CRC code is calculated on 64 data bits. The CRC code is calculated according to CCITT / ISO 3309 - 1984 standards. See figure 5 for principle block schematic and generating polynomial of the CRC code.

Start and stop bits

Start bit is set to logic 1 and stop bit is set to logic 0.

CRC Block Diagram



RF Interface

Resonant capacitor, Rectifier, Limiter and Modulator Switch form the unit which is interfacing to the incoming RF signal. These blocks are interdependent so they are developed as unit. They interface to the antenna which typical characteristics are:

L _S ≈ 1400 nH
$R_S \approx 3 \text{ Ohms}$
$20 \neq 0 \neq 40 \text{ of } 12 \text{ F}$

30 < Q < 40 at 13.56 MHz.

Resonant Capacitor

The capacitor value is adjusted by laser fusing. It can be trimmed by 1pF steps to achieve the absolute value of 94.5pF typically. This option, which is available on request, allows a smaller capacitor tolerance over the whole production.

Rectifier and Limiter

A full wave rectifier (Graetz Bridge) is used to provide supply voltage to the IC. The reverse breakdown of the diodes is also used to protect the IC from overvoltages.



Modulator Switch

Due to the low impedance of the antenna and resonant capacitor the Modulator Switch has to present low RF impedance when switched ON (about 100 ohms).

The minimum time period with the Modulator Switch ON is 38 μ s. At lower data rates this time is even much longer. The current consumption of divider chain running at 13 MHz is near 60 μ A. Putting together this two figures it is clear that it is not possible to supply the IC during the time the Modulator Switch is ON from the integrated Supply Buffer Capacitor which value is approximately 140 pF. The IC has to get power from the RF field also during the time the Modulator Switch is ON.

This problem is solved by putting the Modulator Switch on the output of the Rectifier (between VDD and VSS) and regulating its ON resistance in function of supply voltage. When the supply voltage is high the ON impedance is low. When the supply voltage drops near the region where the operation of the IC at 13.56 MHz is not guaranteed the ON impedance is increased in order to prevent further drop.



Power Supply Management

For a correct operation, the device must be initialised. When the transponder is put in the RF field, the supply voltage increases until it achieves Vr limit (see Figure 7). During this time and for an additionnal 64 bit period, the modulator switch is on and the device initialises its internal logic. At this point, the data transmission starts and runs while the supply voltage is higher than Vmin. If the supply voltage decreases under this limit, the device is again in an initialising state and the modulator is on.





Fig. 7

Miller Encoder

The input to Miller encoder is NRZ data coming from LROM. The output is coded according to Miller format and is driving the modulator Switch. See figure 6 for example of Miller code.

Clock Generation

The clock of the logic is extracted from the RF signal. The clock extracted from RF signal is driving the divider chain consisting of toggle flip-flops. The output of this divider chain is data clock with which the data from Laser ROM (LROM) is addressed, encoded and sent to Modulator Switch.

The layout of divider chain is designed in a way that different data rates can be chosen with metal mask (options).

The following division factors are possible on request: 128, 256, 1024, 2048, 4094 and 8192. The standard is 512.

Others

As mentioned in Output Sequence, during the pause (LW) the Modulator Switch is OFF. When observing the pause duration one has to remember that the time with Modulator Switch OFF effectively observed can vary due to different terminations of STDMS. The stop bit at 0 can be represented either by Modulator Switch ON or OFF depending on the data. The start bit at 1 adds 1/2 of data period OFF (transition in the middle of bit period).

Figure below show the four possible terminations of STDMS and its influence on entire period passed by Modulator Switch OFF. Level LOW represents Modulator Switch OFF. LDB stands for last data bit.





Fig. 8



Pad Description

Name	Description
C2	connection to antenna
C1	connection to antenna
VDD	positive supply
Tout	test output
TESTn	test input with pull up
VSS	negative supply

Package Information





Pad position





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Fig. 9



Ordering Information

Die Form

This chart shows general offering; for detailed Part Number to order, please see the table "Standard Versions" below.



Packaged Devices

This chart shows general offering; for detailed Part Number to order, please see the table "Standard Versions" below.



Remarks:

- For ordering please use table of "Standard Version" table below.
- For specifications of Delivery Form, including gold bumps, tape and bulk, as well as possible other delivery form or packages, please contact EM Microelectronic-Marin S.A.
- Note 1: This is a non-standard package. Please contact EM Microelectronic-Marin S.A for availability.

Standard Versions:

The versions below are considered standards and should be readily available. For other versions or other delivery form, please contact EM Microelectronic-Marin S.A. Please make sure to give complete part number when ordering (without space between letters).

Part Number	Bit coding	Cycle/ bit	Package/Die Form	Delivery Form /	For EM inter only	nal use
				Bumping	old version	OPS#
EM4006 F9 CB2RC	Miller	512	PCB Package, 2 pins	bulk	501	2878
EM4006 F9 CI2LC	Miller	512	CID package, 2 pins (length 2.5mm)	bulk	501	2930
EM4006 F9 WP7	Miller	512	Die in waffle pack, 7 mils	no bumps	501	3669
EM4006 F9 YYY-%%%	Miller	512	custom	custom	%%%	

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